

**30V N & P Pair Enhancement Mode MOSFET**

**N & P Channel Enhancement Mode**

**■ DESCRIPTION**

The STC4545 is the N & P-Channel enhancement mode power field effect transistor is produced using high cell density advanced trench technology to provide excellent  $R_{DS(ON)}$ .

This device is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters applications.

**STC4545M-TRG ROHS Compliant This is Halogen Free**

**■ FEATURE**
**N-Channel**

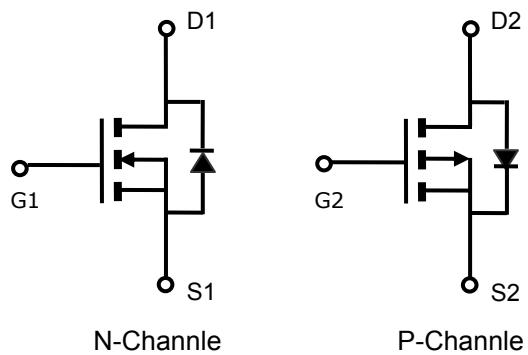
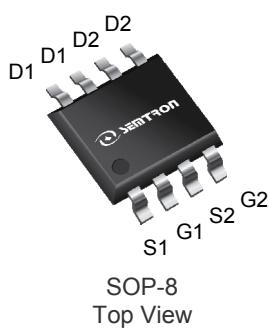
- ◆ 30V / 6.8A,  $R_{DS(ON)} = 18m\Omega$ (typ.)@ $V_{GS} = 10V$
- ◆ 30V / 6.0A,  $R_{DS(ON)} = 26m\Omega$ (typ.)@ $V_{GS} = 4.5V$

**P-Channel**

- ◆ -30V / -6.5A,  $R_{DS(ON)} = 35m\Omega$ (typ.)@ $V_{GS} = -10V$
- ◆ -30V / -5.0A,  $R_{DS(ON)} = 58m\Omega$ (typ.)@ $V_{GS} = -4.5V$
- ◆ Super high density cell design for extremely low  $R_{DS(ON)}$
- ◆ Fast switching performance.

**■ APPLICATIONS**

- ◆ Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.
- ◆ High Frequency Synchronous Buck DC-DC Converter.


**■ PIN CONFIGURATION**

**■ PART NUMBER INFORMATION**

**ST C 4545 M - TR G**  
 a b c d e f

a : Company name.  
 b : Channel type.  
 c : Product Serial number.  
 d : Package code  
 e : Handling code  
 f : Green product code

## ■ ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
STC4545M-TRG	M : SOP-8	TR : Tape&Reel	2.5K/Reel

※ Year Code : 00 ~ 90, 2010 : 00

※ Week Code : 01 ~ 54

※ SOP-8 : Only available in tape and reel packaging.

## ■ ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Typical		Unit
		N	P	
$V_{DSS}$	Drain-Source Voltage	30	-30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	$\pm 20$	V
$I_D$	Continuous Drain Current, $V_{GS}=10\text{V}^A$	$T_A=25^\circ\text{C}$	6.8	-6.5
		$T_A=70^\circ\text{C}$	6.2	-5.8
$I_{DM}$	Pulsed Drain Current <sup>B</sup>	25	-25	A
$E_{AS}$	Single Pulse Avalanche Energy L=0.1mH <sup>C</sup>	27	37	mJ
$I_{AS}$	Avalanche Current	12.8	-15.2	A
$P_D$	Power Dissipation	$T_A=25^\circ\text{C}$	2.0	2.0
		$T_A=70^\circ\text{C}$	1.4	1.4
$T_J$	Operation Junction Temperature	-55/150		°C
$T_{STG}$	Storage Temperature Range	-55/150		°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

## ■ THERMAL DATA

Symbol	Parameter	Min	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient <sup>A</sup> Steady-State			85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Lead <sup>A</sup> Steady-State			60	°C/W

**N-CHANNEL ELECTRICAL CHARACTERISTICS**
*(TA = 25°C Unless otherwise noted )*

Symbol	Parameter	Condition	Min	Typ	Max	Unit	
<b>Static Parameters</b>							
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30			V	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0		2.0	V	
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C			1	μA	
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			5		
R <sub>DSON</sub>	Drain-source On-Resistance <sup>B</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =6.8A V <sub>GS</sub> =4.5V, I <sub>D</sub> =6.0A	18 26	22 36	mΩ		
G <sub>f</sub>	Forward Transconductance	V <sub>DS</sub> =5.0V, I <sub>D</sub> =6.8A		5.6		S	
<b>Source-Drain Diode</b>							
V <sub>SD</sub>	Diode Forward Voltage <sup>B</sup>	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V			1.2	V	
I <sub>S</sub>	Continuous Source Current <sup>AD</sup>				6.2	A	
<b>Dynamic Parameters</b>							
Q <sub>g</sub> (4.5V)	Total Gate Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V I <sub>D</sub> =6.0A		4.9	7.0	nC	
Q <sub>gs</sub>	Gate-Source Charge			1.5			
Q <sub>gd</sub>	Gate-Drain Charge			1.86			
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V f =1MHz		418	588	pF	
C <sub>oss</sub>	Output Capacitance			65			
C <sub>rss</sub>	Reverse Transfer Capacitance			52			
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =15V, V <sub>GEN</sub> =10V, R <sub>G</sub> =3.3Ω,		2.2		nS	
t <sub>r</sub>				37			
t <sub>d(off)</sub>	Turn-Off Time			12.2			
t <sub>f</sub>				4.8			

Note:

- A. The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with TA=25°C.
- B. The data tested by pulsed , pulse width ≤ 300uS , duty cycle ≤ 2%
- C. The EAS data shows Max. rating . The N Channel test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH.
- D. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date

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**P-CHANNEL ELECTRICAL CHARACTERISTICS**
*(TA = 25°C Unless otherwise noted )*

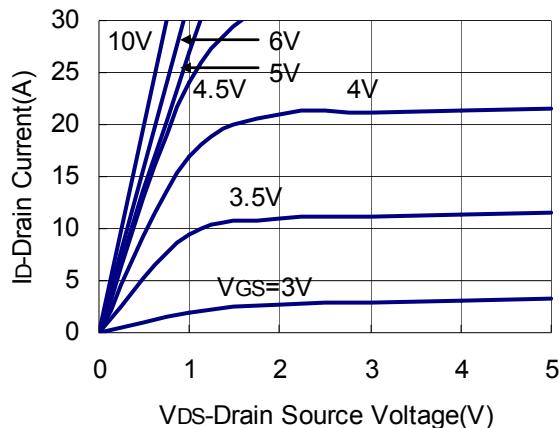
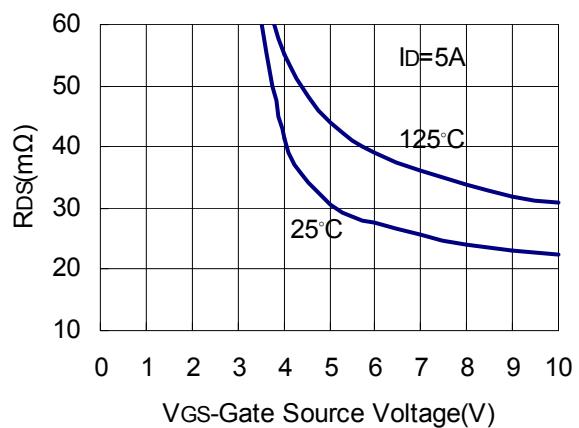
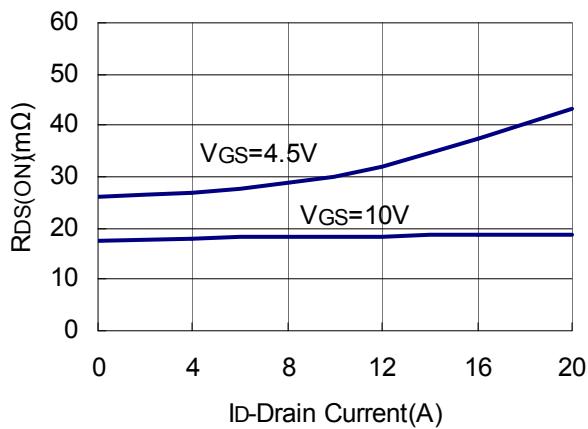
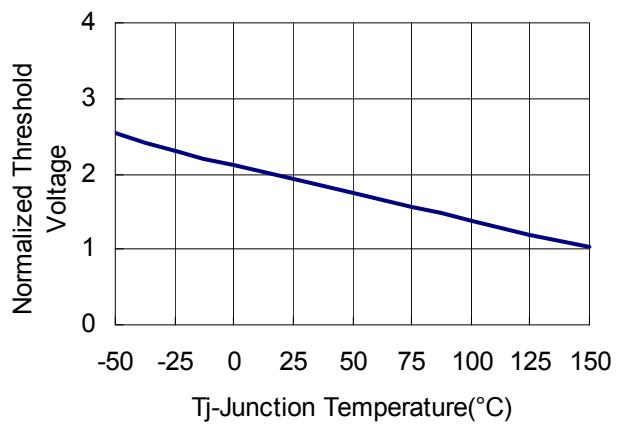
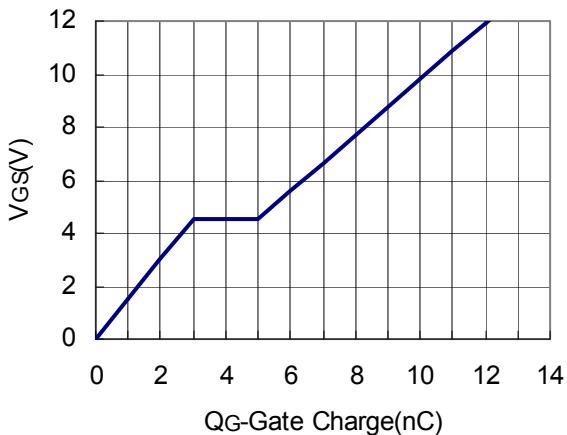
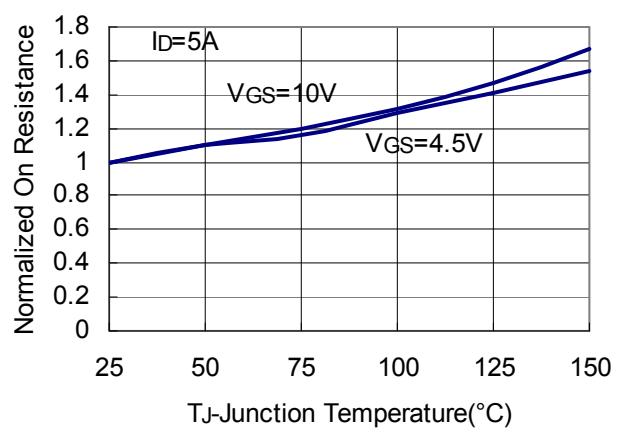
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
<b>Static Parameters</b>							
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	-30			V	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	-1.0		-2.0	V	
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C			-1	μA	
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-5		
R <sub>DSON</sub>	Drain-source On-Resistance <sup>B</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-6.5 A V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5.0A	35 58	40 70		mΩ	
G <sub>f</sub>	Forward Transconductance	V <sub>DS</sub> =-5.0V, I <sub>D</sub> =-7A		6		S	
<b>Source-Drain Diode</b>							
V <sub>SD</sub>	Diode Forward Voltage <sup>B</sup>	I <sub>S</sub> =-1.0A, V <sub>GS</sub> =0V			-1.2	V	
I <sub>S</sub>	Continuous Source Current <sup>AD</sup>				-6.0	A	
<b>Dynamic Parameters</b>							
Q <sub>g</sub> (4.5V)	Total Gate Charge	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-4.5V I <sub>D</sub> =-5.0A		6.5	7.2	nC	
Q <sub>gs</sub>	Gate-Source Charge			2.8			
Q <sub>gd</sub>	Gate-Drain Charge			3.2			
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V f =1MHz		648	685	pF	
C <sub>oss</sub>	Output Capacitance			270			
C <sub>rss</sub>	Reverse Transfer Capacitance			105			
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =-15V, V <sub>GEN</sub> =-10V, R <sub>G</sub> =3.3Ω,		9.0		nS	
t <sub>r</sub>				16.8			
t <sub>d(off)</sub>	Turn-Off Time			22			
t <sub>f</sub>				22.6			

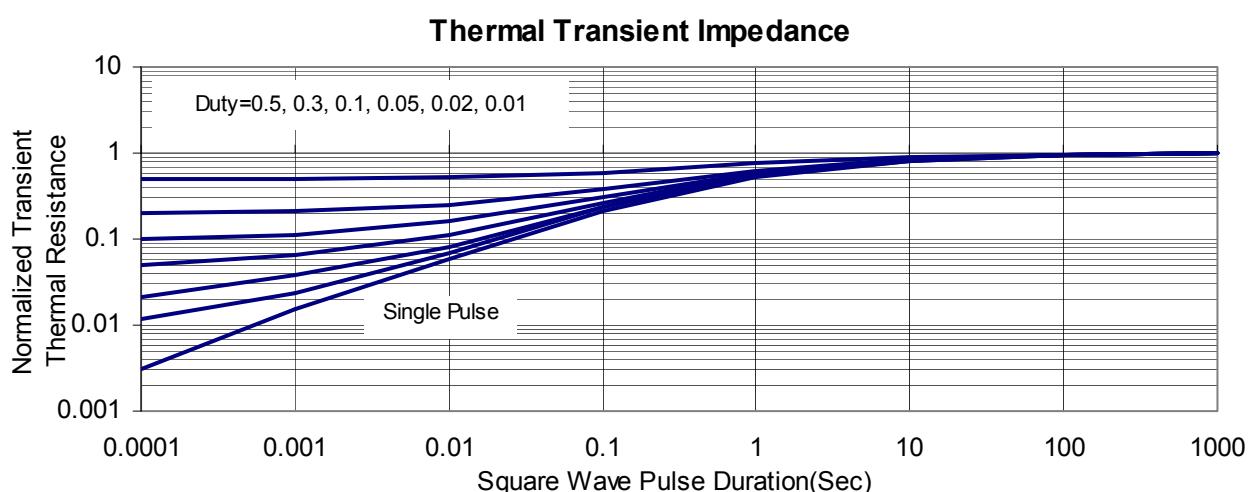
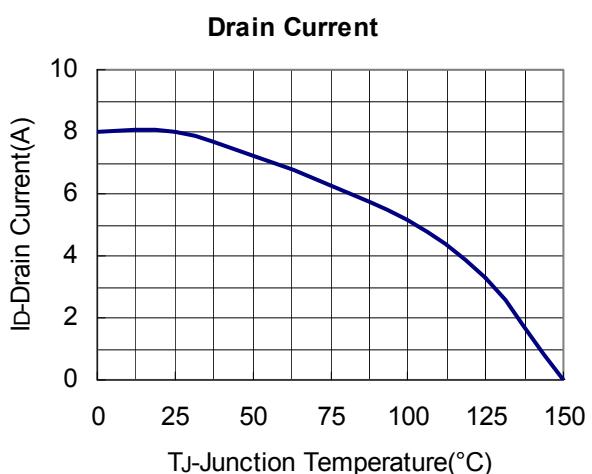
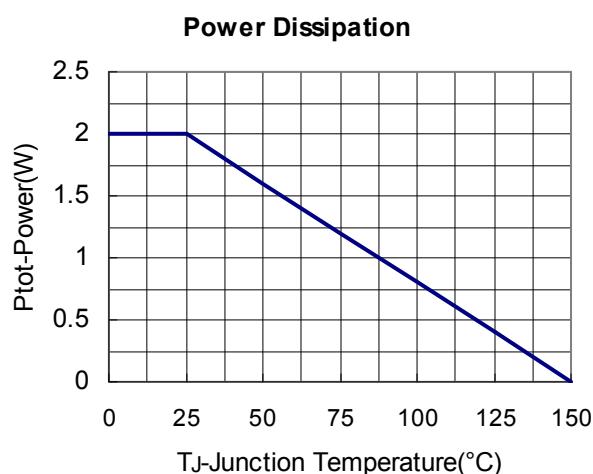
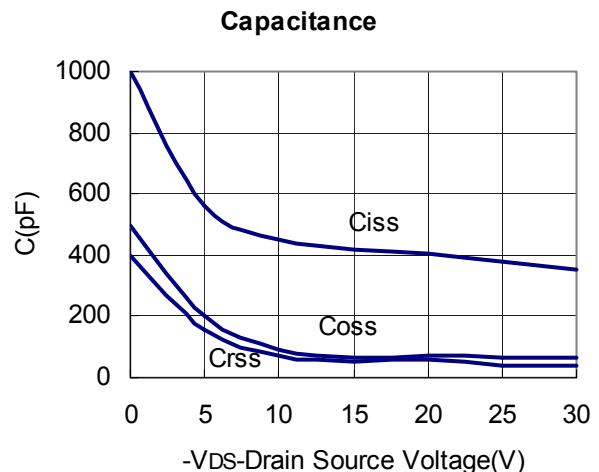
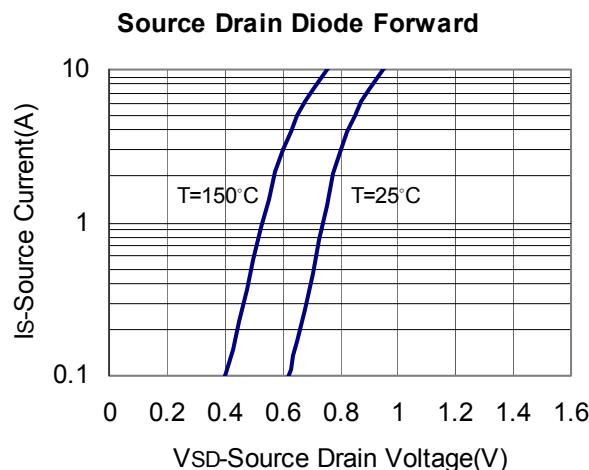
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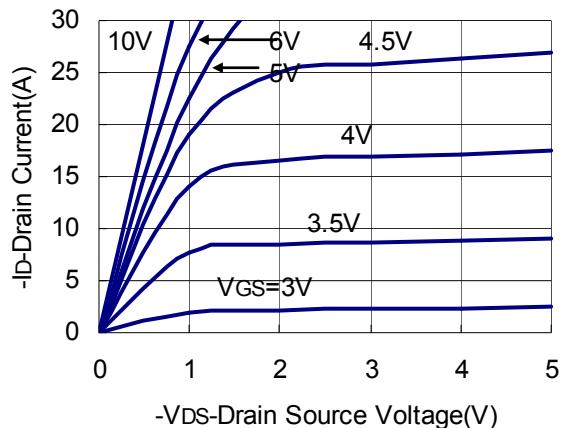
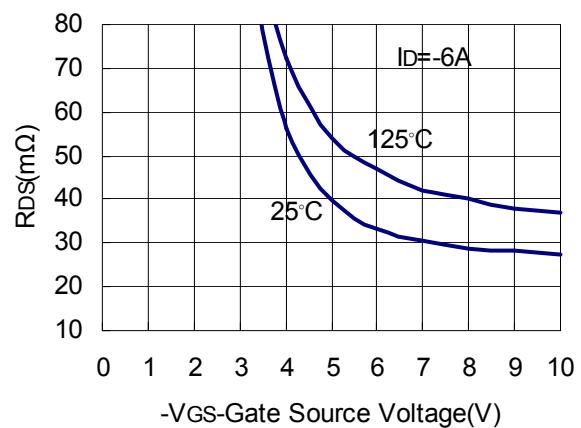
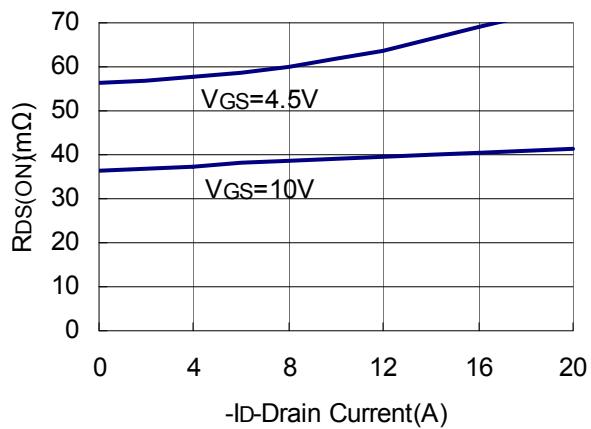
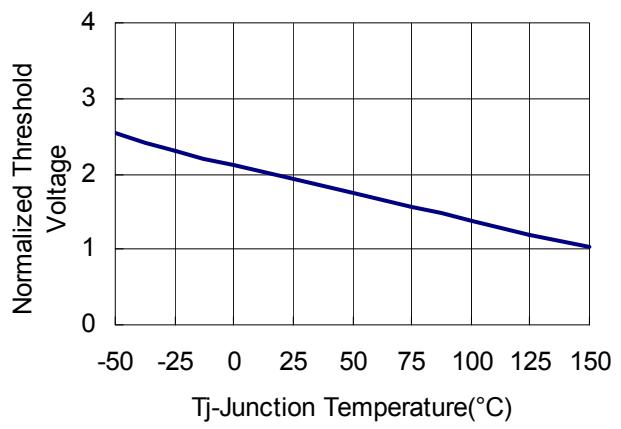
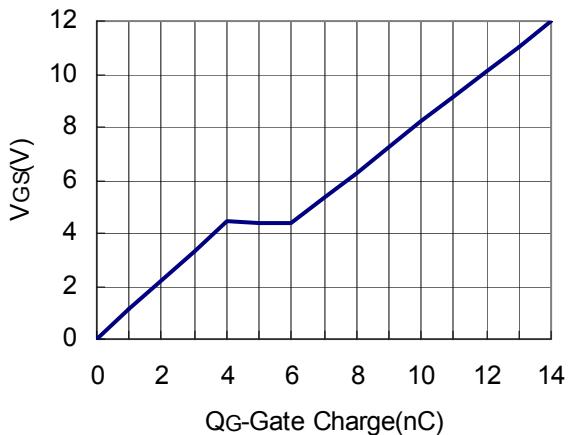
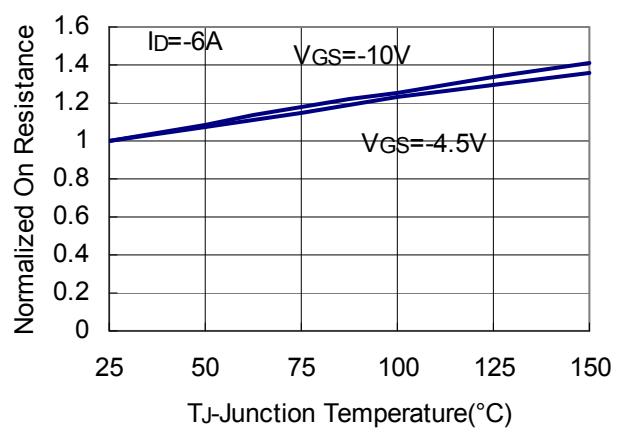
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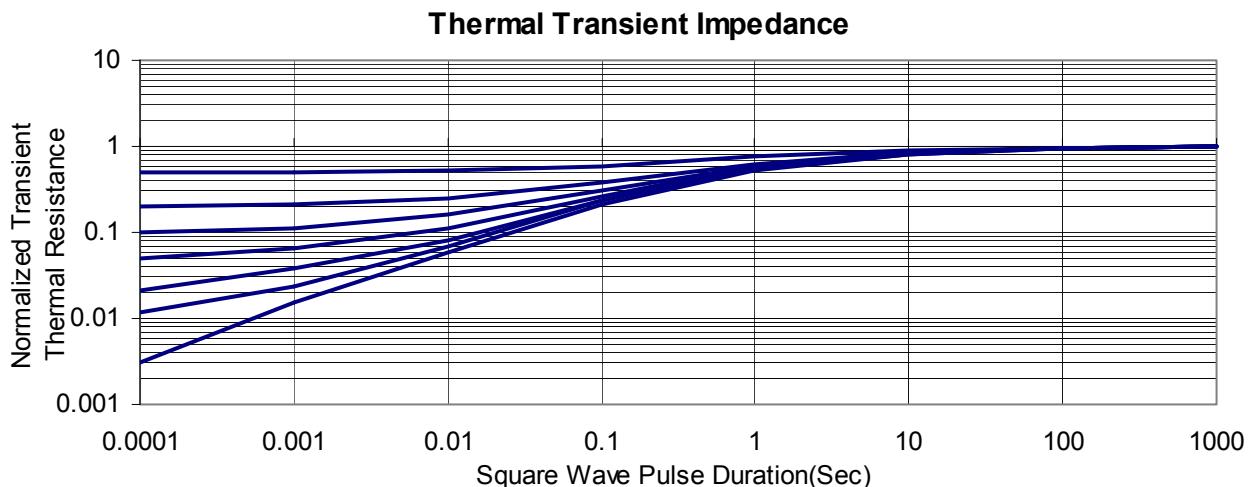
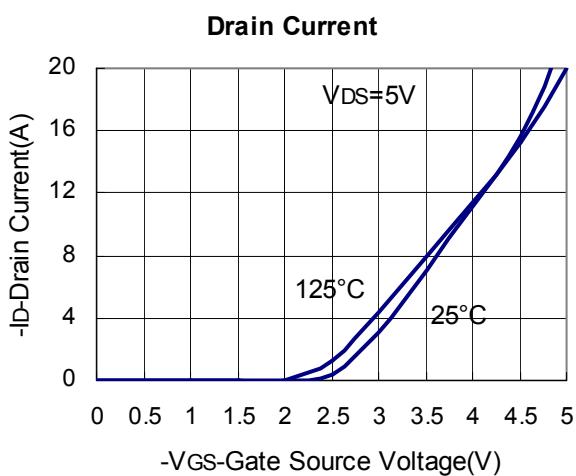
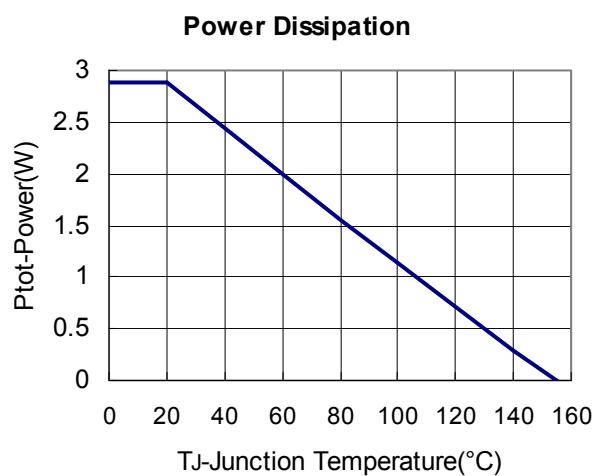
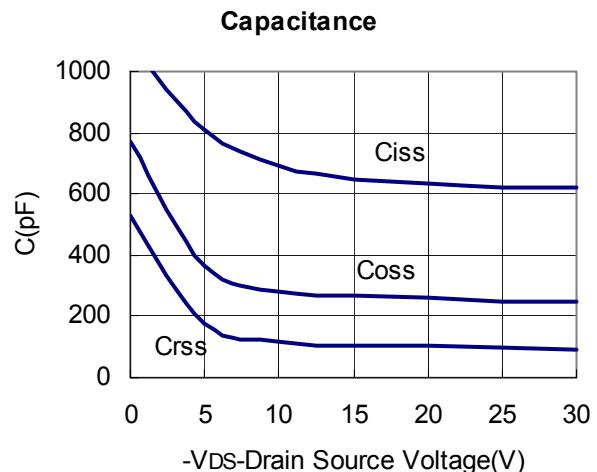
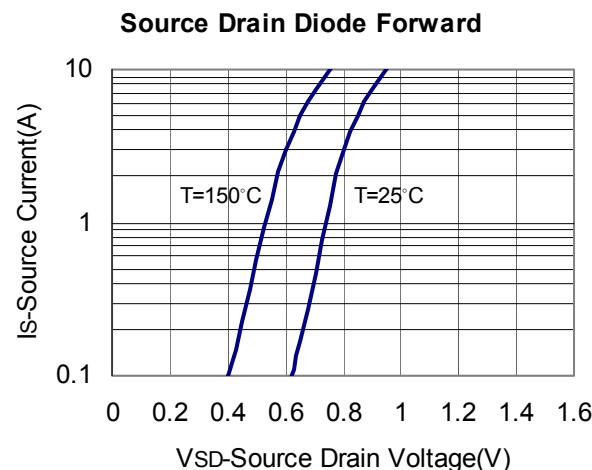
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**TYPICAL CHARACTERISTICS(N-Channel)**
**Output Characteristics**

**Drain-Source On Resistance**

**Drain Source On Resistance**

**Gate Threshold Voltage**

**Gate Charge**

**Drain Source On Resistance**


**TYPICAL CHARACTERISTICS(N-Channel)**


**TYPICAL CHARACTERISTICS(P-Channel)**
**Output Characteristics**

**Drain-Source On Resistance**

**Drain Source On Resistance**

**Gate Threshold Voltage**

**Gate Charge**

**Drain Source On Resistance**


**TYPICAL CHARACTERISTICS(P-Channel)**


**SOP-8 PACKAGE DIMENSIONS**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.040	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
$\theta$	$0^\circ$	$8^\circ$	$0^\circ$	$8^\circ$

